PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TAKUMA OKUBO	02/25/2021
KENJI OHATA	02/25/2021
AKIHITO YAMADA	03/01/2021

RECEIVING PARTY DATA

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State/Country:	JAPAN	
Postal Code:	1730001	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17273437

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NAME OF SUBMITTER:	CHRISTOPHER J. MAIER	
SIGNATURE:	/Christopher J. Maier/	
DATE SIGNED:	03/04/2021	

Total Attachments: 3

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> **PATENT** REEL: 055495 FRAME: 0754 506537348

Docket No.: 11320023US Only After Sept 16, 2012 US Rights Only

ASSIGNMENT WITH DECLARATION FOR PATENT APPLICATION (37 CFR 1.63)

特許出願宣言書付き譲渡書 (37 CFR 1.63)

Japanese Language Assignment with Declaration

下記に署名した発明者であり、以下に譲渡人と称される私 (我々)は、下記の出願に記載された改良に関する発明を し、	Whereas, I/We, the undersigned inventor(s) hereinafter called assignor(s), have invented certain improvements described in the application identified below; and
の(譲受人)は、本件出願 および本件発明、ならびに当該出願から得られるいかなる米 国特許に関する全ての権利、権原、および利益の取得を要求 します。	Whereas, <u>LINTEC Corporation</u> of <u>23-23</u> , <u>Honcho</u> , <u>Itabashi-ku</u> , <u>Tokyo 1730001</u> , <u>Japan</u> , (assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;
よって、価値ある対価の受領をここに確認し、	Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,
上で譲渡人として指名された私(我々)は、米国における本件出願およびその発明開示、全ての分割出願および継続出願、これら出願について許可された米国特許証および全ての再発行特許に関する全ての権利(35 USC 119に基づく優先権を主張する権利と過去分の損害賠償請求権を含む)、権原、および利益を、上で指定した譲受人、その承継人ないし権利承継者に売却、譲渡、移転するとともに、私(我々)は米国特許商標庁長官に対し、本件出願に記載の発明に対する特許証を、譲受人、その承継人ないし権利承継者に発行することを要請し、私(我々)は、これ以上の対価なしに、譲受人の求めにより、本件米国特許出願に関して譲受人が必要とみなす全ての書類を作成します。	I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including all divisions, and continuations thereof, and all Letters Patent of the United States that may be granted thereon, and all reissues thereof, including the right to claim priority under 35 USC 119 and the right to sue for past damages, and I/we request the Director of the U.S. Patent and Trademark Office to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.
(公証人による認証は不要であるが、これらの書類は、35 USC 261に基づく推定された証拠となる)	(Legalization not required for recording but is prima facie evidence of execution under 35 USC 261)
私は, 下記に記載の発明者として, 以下の通り宣言します。	As the below named inventor, I hereby declare that:
 本宣言付き譲渡書は、以下に関します。	This assignment with declaration is directed to:
添付の出願書、または、	The attached application, or
2019年9月4日に出願された米国出願あるいは PCT 国際 出願番号 PCT/JP2019/034839(確認番号)	X United States Application or PCT International Application Number PCT/JP2019/034839 filed on September 4, 2019 (Confirmation No. <u>7073</u>).
 本件出願の名称は、以下の通りです。	The application is entitled:
剥離ライナー、剥離ライナーの作製方法、粘着シート、	RELEASE LINER, METHOD FOR PRODUCING RELEASE
および粘着シートの作製方法	LINER, PRESSURE-SENSITIVE ADHESIVE SHEET, AND METHOD FOR PRODUCING PRESSURE-SENSITIVE ADHESIVE SHEET

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PATENT REEL: 055495 FRAME: 0755

Japanese Language Assignment with Declaration

上記に明示された出願は, 私が作成した、または作成を許可 したものです。

私は、本件出願において請求項に記載された発明の本来の発 明者、または、本来の共同発明者であると信じています。

私は、本宣言付き譲渡書の提出に関わる本件出願の内容を検 討し、理解しています。

私は、37 CFR 1.56に定義されるように、自身が知る全ての 特許性に関する重要な情報を、米国特許商標庁に開示する義 務があることを認識しています。

私は、本宣言付き譲渡書において故意に虚偽の供述を行った 場合、18 USC 1001に基づき、罰金あるいは5年以下の懲役、 または両方による処罰の対象となることを認識しています。 The above identified application was made or was authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I have reviewed and understand the contents of the application for which this assignment with declaration is being submitted.

I am aware of the duty to disclose to the Office all information known to me to be material to patentability as defined in 37 CFR 1.56.

I hereby acknowledge that any willful false statement made in this assignment with declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

STATEMENT OF ACCURATE TRANSLATION IN ACCORDANCE WITH 37 CFR 1.69(b):

The assignment with declaration is an accurate translation of the corresponding English language assignment with declaration.

Signature

Date

March 11, 2014

NAME OF SOILE OR FIRST INVESTOR: # 合わらは悪からの場合 Given Name (first and middle (f say)) **A (名かよびミドルキー人(影響する場合))** Taiguma** Taiguma** Taiguma*		
報一あさいは第一の影明者名 「New Name (Brand middle [Efary]) 「Name (Brand middle [Efary]) Name (Or THIRD INVENTOR: 第 ○ 0 LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Name (Brand Middle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary]) A (Rak 1/5 P/A — A [Egiry Tokyo 1730001] Name (Brand Midlle [Efary Tokyo 1730001] Name (B	NAME OF SOLE OR FIRST INVENTOR:	
Residence 日本	唯一あるいは第一の発明者名	
# OKUBO Internate Signature #州教育等名 Takuma Okubo Residence: #研究の著名 Takuma Okubo Residence: ##所示の Internate Signature ##の Okubre Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Family Name or Surname	Given Name (first and middle [if any])	Family Name or Surname
Description of Signature Properties	タ (タおとびこドルネーム[該当する場合])	性 OKUBO
Residence (do LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Masling Address (do LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF SECOND INVENTOR:		Date
Residence: 住所: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 第2年: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF SECOND INVENTOR: 第二の参照者名 Given Name (first and middle [if say)) Konji Investor's signature ARJ の	3600 to 500 T	1月付 Fehicary 95 2021
### Out LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address:		1 Copusity 2.
Matting Address: 考法: (d) LINTEC Corporation, 23-23, Honcho, Inbasshi-ku, Tokyo 1730001, Japan NAME OF SECOND INVENTOR: おこの影響名名 Given Name (first and middle [if any)) (を含ましてミトルネール(熱学であ場合)) Residence: (お) (LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF SECOND INVENTOR: Residence: (お) (LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF THIRD INVENTOR: 第2年 (今もLINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF THIRD INVENTOR: 第2年 (今もLINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF THIRD INVENTOR: 第2年 (今は大学・大学・人様博士を報金) Akihito Newtor's signature 東明者の書名 Akihito A	A.T.	4-0004 Y
解表生: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF SECOND INVENTOR: 第二の場所者 Given Name (first and middle (if any)) 在 名表となどとからから 人民当子の場合) Kenji	c/o LINTEC Corporation, 23-23, Honono, Itabasm-ku, Tokyo	5 1730001, Japan
NAME OF SECOND INVENTOR: 第一の東側着名 「Given Name (first and middle [if snyt)] を (名およびミドルネーム[該当する場合)) を (名およびミドルネーム[該当する場合))	TO 144 14 .	
第二の製剤者名 Given Name (first and middle [if say)) Kenji Inventor's signature 発明者の報名 Kenji Ohota Residance: 佐所: claintee Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 新送先: claintee Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 新送先: claintee Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF THIRD INVENTOR: Given Name (first and middle [if say)) A (名23-10-5) ドルネー人[統当する場合]) Akihito Pamily Name or Survance ### YAMADA Pamily Name or Survance ### YAMADA Pamily Name or Survance ### YAMADA Date Bif March 202 Residence: #### Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: #### ### ### ### ### ### ### ### ###	. c/o LINTEC Corporation, 23-23, Holicito, Itabashi-ku	i, Tokyo 1730001, Japan
Given Name (first and middle [if sny]) 名(名およびミドルネー人(禁当する場合)) 名(たままびミドルネー人(禁当する場合)) Kenji OHATA Date 自付 February 25, 2021 Residence 住所: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 第12 先: 第12 外書 第2 外間名 Given Name (first and middle (if sny)) Akihito Family Name or Surname 東州省の報名 Akihito Family Name or Surname A		
接 OHATA Inventor's signature 表現者の署名		Family Name or Surname
Inventor's signature 提明者の報名 Country Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Melitag Address:	【タ (タセトバミドルネート[該当する場合])	沙生
Residence: (方の LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF THERD INVENTOR: 第2次 受明者の署名 (今3よびラドルネー人(数省する場合)) Akthito Pamaya 日村 March 1, 2021 Residence: 使用: のしまいすのでは、23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF THERD INVENTOR: 第2次 受明者の署名 (今3よびラドルネー人(数省する場合)) Akthito Pamaya 日村 March 1, 2021 Residence: 使用: のしまれずの景名 Residence: 使用: のしまれずの景名 Akthito Yamaya Mailing Address: 第2次: のしまれずをCorporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 第2次: のしまれずをCorporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan	Kenji	OHATA
Residence: (た形: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Malling Addres: 第述条: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAMB OF THIRD INVENTOR: 第二の契明者名 Given Name (first and middle [if any!)	双阳字の関々 ノー・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・	
接所: of LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 動送先: of LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan NAME OF THIRD INVENTOR: 第二の光明音名 名 (名およびミドルネーム[該当する場合]) Akihito Inventor's signature 表別者の署名 Akihito Residence: 任所: of LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 第送先: of LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan	Lenji Uhata	1 edruary 23, 2021
Malling Address: Making Address		Ţ
解送完:	c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo	o 1730001, Japan
NAME OF THIRD INVENTOR: 第三の受明者名 Given Name (first and middle [if any!) A (水およびミドルネーム誘導する場合!) Akihito Yamada Btt March 1, 2021 Inventor's signature 発明者の署名 Residence: 住所: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 新途光: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan		
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A (名およびミドルネーム[該当する場合]) Akihito Yamada Date 日付 March 1, 2021 Residence: (七所: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan Mailing Address: 郷送先: c/o LINTEC Corporation, 23-23, Honcho, Itabashi-ku, Tokyo 1730001, Japan	第三の発明者名 	
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Residence: 住所:	名(名およびミドルネーム[該当する場合]) Akihito	YAMADA
Residence: 住所:	Inventor's signature	Date Date
性所:	^{発明者の署名}	March 1, 2021
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c/o LINTEC Corporation, 23-23, Honeno, Itaoasm-kii, Tokyo 1730001, Japan		
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